

# User Manual

## DA14681 to DA14683 Porting Guide

UM-B-097

### **Abstract**

*This is a guide explaining the porting from DA14681 to DA14683 silicon version.*

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## Contents

|                                   |    |
|-----------------------------------|----|
| Abstract .....                    | 1  |
| Contents .....                    | 2  |
| Figures.....                      | 2  |
| 1 References .....                | 3  |
| 2 Introduction.....               | 4  |
| 3 Target Configuration.....       | 4  |
| 4 Memory Optimization.....        | 8  |
| 5 GPIO Adapter .....              | 8  |
| 6 Wearable Reference design ..... | 8  |
| 6.1 Partition Table .....         | 8  |
| Revision History .....            | 10 |

## Figures

|  |   |
|--|---|
| Figure 1: Configuration manager Selection..... | 4 |
| Figure 2: Create new configuration .....       | 4 |
| Figure 3: Select configuration base.....       | 5 |
| Figure 4: Edit project properties .....        | 5 |
| Figure 5: Edit assembly defined symbols.....   | 6 |
| Figure 6: Edit compiler defined symbols .....  | 6 |
| Figure 7: Edit Pre-build configuration .....   | 7 |
| Figure 8: Edit linker configuration.....       | 8 |

## 1 References

- [1] UM-B-044, DA1468x Software Platform Reference, User Manual, Dialog Semiconductor.

## 2 Introduction

This document explains the changes and steps needed for porting an application developed on the DA14681 SDK 1.0.12 release to the DA14683 SDK1.0.12 release.

## 3 Target Configuration

The application developed on the DA14681 SDK shall be compiled to target the DA14683-00 silicon version, and it can be achieved by adding a new building configuration to the existing application in the following steps.

1. Open the configuration manager (Figure 1) and select a new configuration (Figure 2).

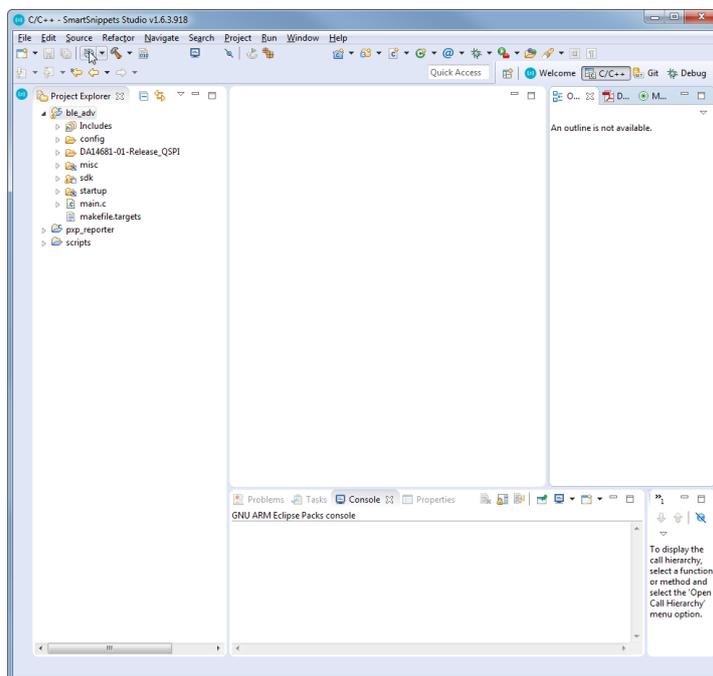


Figure 1: Configuration manager Selection

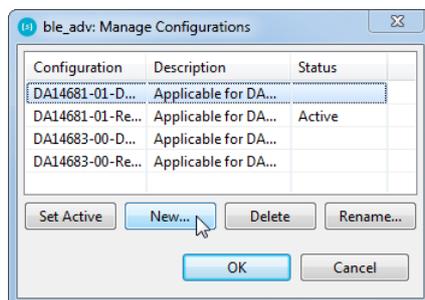
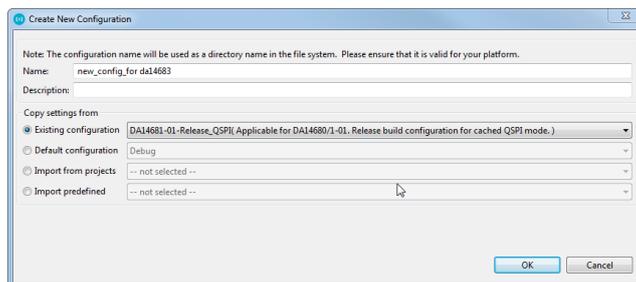


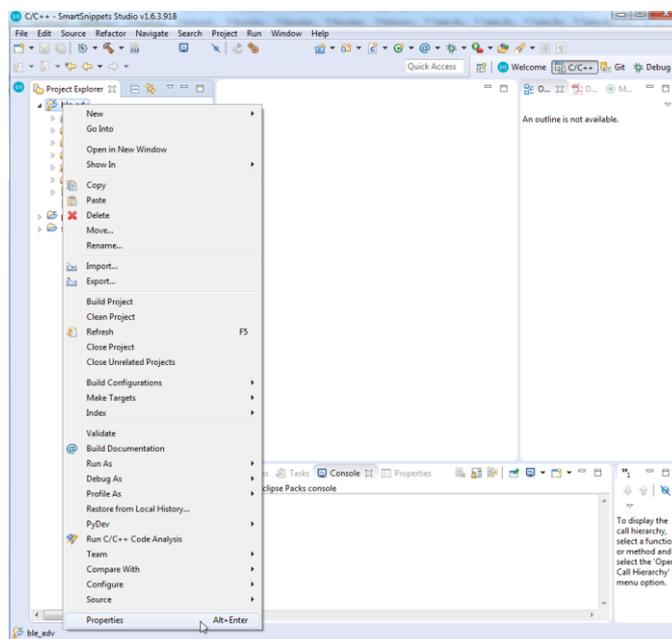
Figure 2: Create new configuration

2. Create a new configuration with the name of your choice and copy the settings from your preferred current configuration (Figure 3).



**Figure 3: Select configuration base**

3. Now you can close the configuration manager.
4. Open the project **Properties** to edit the new configuration with a right click on the application project (Figure 4).



**Figure 4: Edit project properties**

5. Make sure the new configuration is selected at the top of the window. In the "**C/C++ Build/Settings**" area, edit the preprocessor setting for both **Cross ARM GNU assembler** (Figure 5) and **Cross ARM C Compiler** (Figure 6). You should edit the IC\_REV and IC\_STEP to reflect the following values:

```
dg_configBLACK_ORCA_IC_REV=BLACK_ORCA_IC_REV_B
```

```
dg_configBLACK_ORCA_IC_STEP=BLACK_ORCA_IC_STEP_B
```

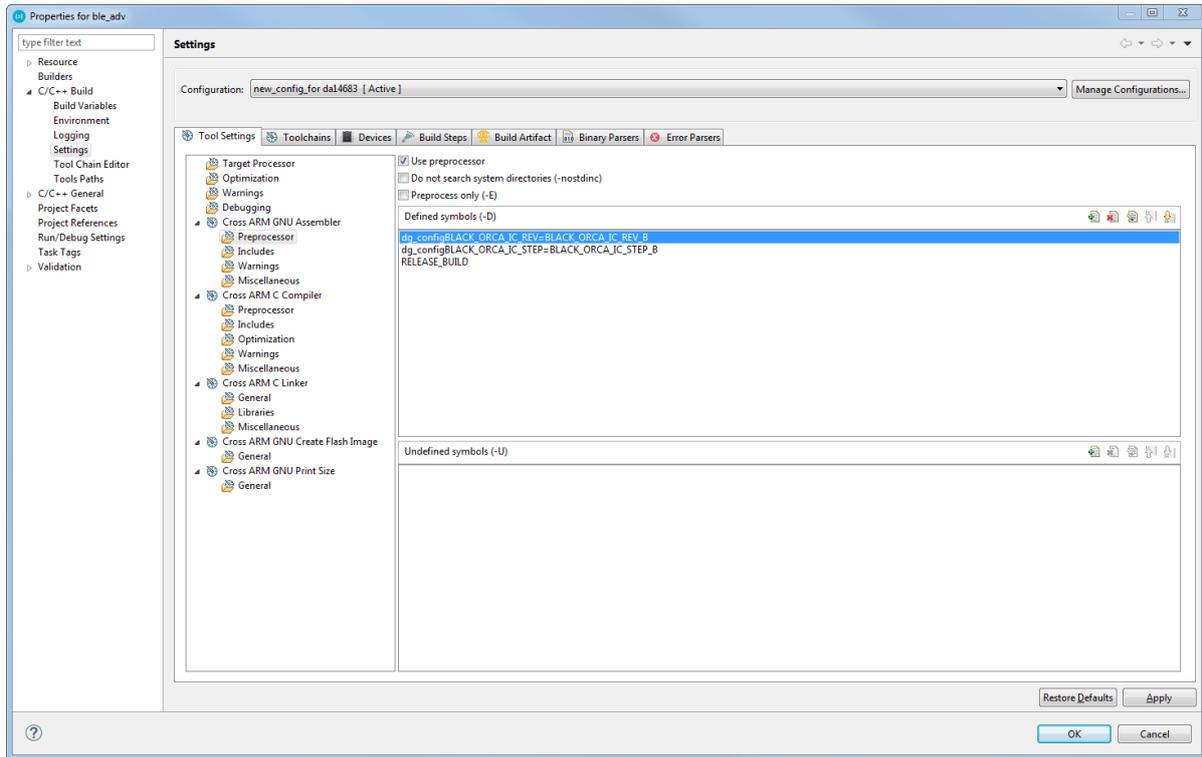


Figure 5: Edit assembly defined symbols

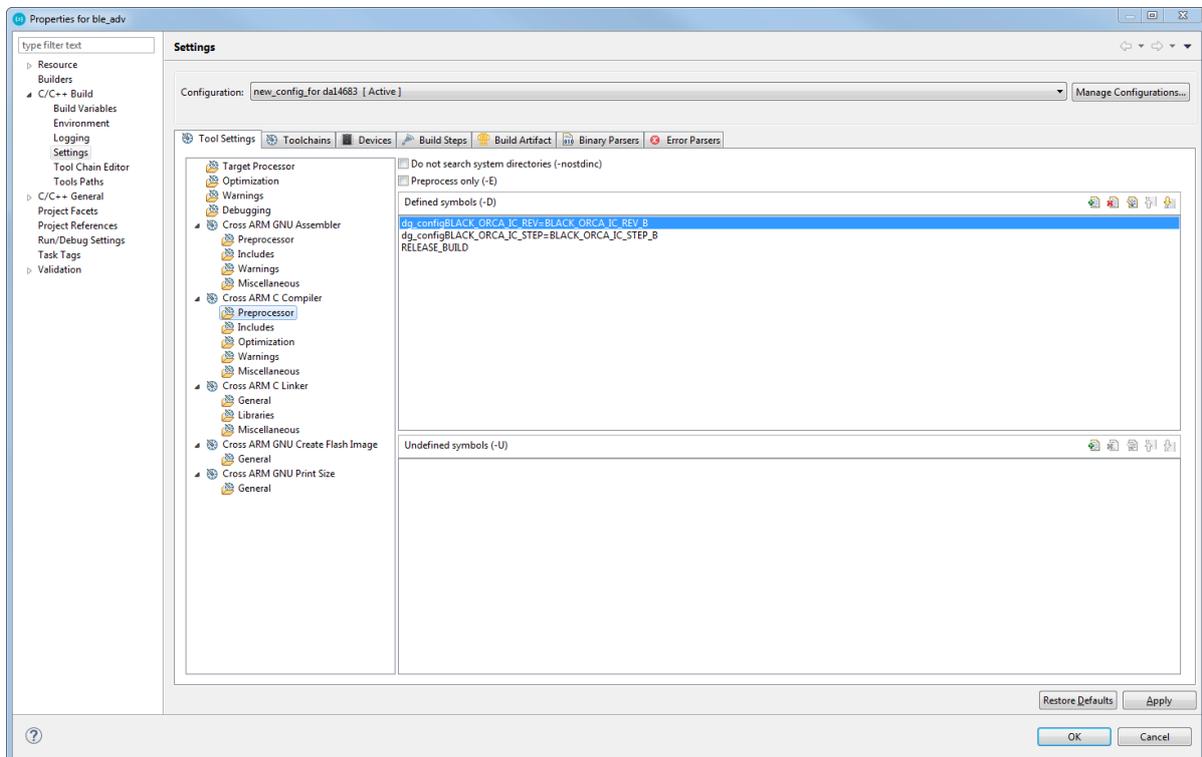


Figure 6: Edit compiler defined symbols

- In the **Build Steps** tab, the command in the **Command** of the **Pre-build Steps** edits the IC revision to match the compiler parameters (Figure 7).

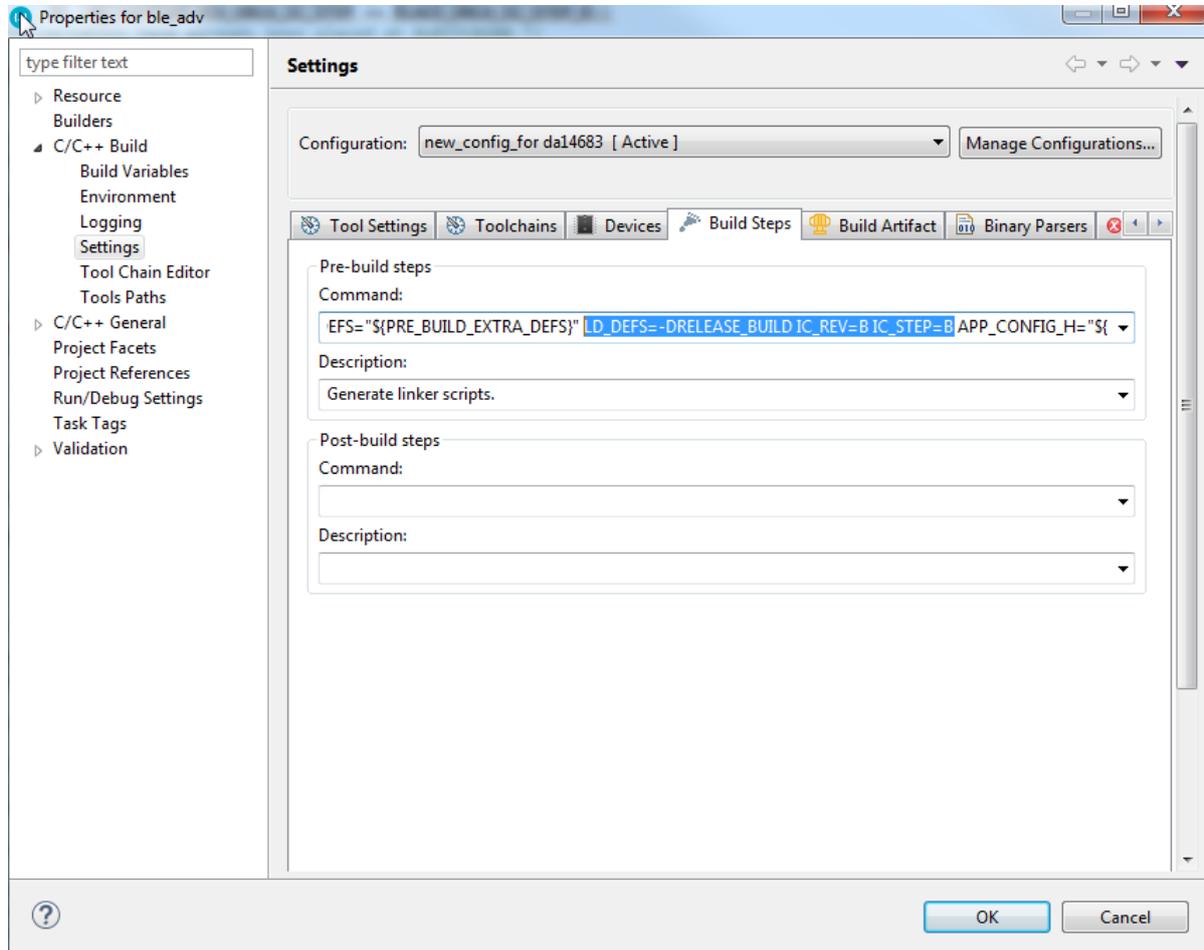


Figure 7: Edit Pre-build configuration

- In the **Libraries** of the **Cross ARM C Linker**, edit the **libraries (-l)** and **Library search path (-L)** to point at the DA14683 SDK (Figure 8).

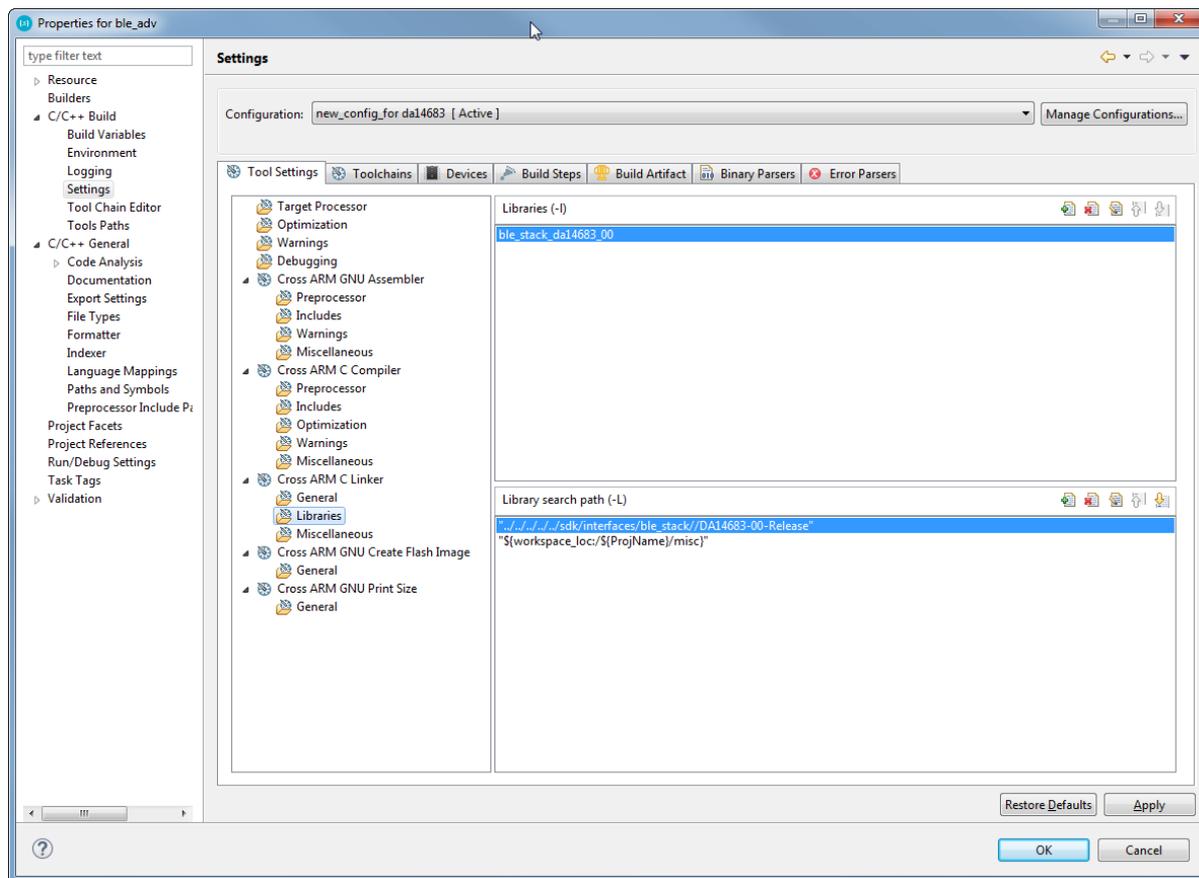


Figure 8: Edit linker configuration

8. Recompile and run your application, which should now be able to run on the DA14683.

## 4 Memory Optimization

Please note that the Bluetooth Low Energy stack in the DA14682/DA14683 uses a different RAM mapping from the DA14680/DA14681. Please refer to [1] Section 13.3 to select the best possible memory retention configuration depending on your application footprint.

## 5 GPIO Adapter

The DA14683 does not support the GPIO event counter that is present on the DA14680/DA14681 and therefore all calls/parameters in `ad_gpio_intr.c` have to be modified so that these elements are only included for DA14680/DA14681 builds.

## 6 Wearable Reference design

### 6.1 Partition Table

In the DA14681 Wearable SDK 1.150.6, the flash partition table (1M) is as follows:

```
PARTITION2( 0x000000 , 0x07F000 , NVMS_FIRMWARE_PART , 0 )
```

```

PARTITION2( 0x07F000 , 0x001000 , NVMS_PARTITION_TABLE      , PARTITION_FLAG_READ_ONLY
)
PARTITION2( 0x080000 , 0x010000 , NVMS_PARAM_PART          , 0 )
PARTITION2( 0x090000 , 0x030000 , NVMS_BIN_PART         , 0 )
PARTITION2( 0x0C0000 , 0x020000 , NVMS_LOG_PART        , 0 )
PARTITION2( 0x0E0000 , 0x020000 , NVMS_GENERIC_PART    , 0 )

```

In the SDK 1.0.10, the flash partition table (1M) is as follows:

```

PARTITION2( 0x000000 , 0x07F000 , NVMS_FIRMWARE_PART    , 0 )
PARTITION2( 0x07F000 , 0x001000 , NVMS_PARTITION_TABLE  , PARTITION_FLAG_READ_ONLY
)
PARTITION2( 0x080000 , 0x010000 , NVMS_PARAM_PART       , 0 )
PARTITION2( 0x090000 , 0x030000 , NVMS_BIN_PART         , 0 )
PARTITION2( 0x0C0000 , 0x020000 , NVMS_LOG_PART        , 0 )
PARTITION2( 0x0E0000 , 0x020000 , NVMS_GENERIC_PART    , PARTITION_FLAG_VES )

```

The SDK 1.0.12 uses VES for the generic partition but the wearable application does not include this module in the configuration settings. To fix this, the `custom_config_qspi.h` file in the Wearable Application was modified as follows:

```
#define dg_configNVMS_VES (1)
```

## Revision History

| Revision | Date        | Description                          |
|----------|-------------|--------------------------------------|
| 1.1      | 20-Jan-2022 | Updated logo, disclaimer, copyright. |
| 1.0      | 14-06-2018  | Initial version.                     |

**Status Definitions**

| Status                  | Definition   |
|-------------------------|--|
| DRAFT                   | The content of this document is under review and subject to formal approval, which may result in modifications or additions. |
| APPROVED<br>or unmarked | The content of this document has been approved for publication.  |